PATENT ASSIGNMENT

Electronic Version v1.1 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Weilin Gao	01/12/2010
Tomotsugu Aoyama	01/12/2010
Hisashi Suda	01/12/2010
Hiroto Narieda	01/12/2010
Akira Sugawara	01/12/2010
Akifumi Onodera	01/12/2010

RECEIVING PARTY DATA

Name:	DOWA METALTECH CO., LTD.	
Street Address:	14-1, Sotokanda 4-chome, Chiyoda-ku	
City:	Tokyo	
State/Country:	JAPAN	
Postal Code:	101-8617	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	12767074

CORRESPONDENCE DATA

(203)865-0297 Fax Number:

Correspondence will be sent via US Mail when the fax attempt is unsuccessful.

Phone: 203-777-6628 Email: reidn@bachlap.com Correspondent Name: Gregory P. LaPointe Address Line 1: 900 Chapel Street

Address Line 4: New Haven, CONNECTICUT 06510

ATTORNEY DOCKET NUMBER: 10-210

PATENT REEL: 024287 FRAME: 0716

Address Line 2: Suite 1201

501157986

NAME OF SUBMITTER:	Gregory P. LaPointe
Total Attachments: 1 source=10-210_Assignment#page1.tif	

PATENT REEL: 024287 FRAME: 0717

Assignment

In consideration of One Dollar (\$1,00), and other good and valuable consideration, the receipt of which is hereby acknowledged, We, the undersigned,

Weilin Gao, Tomotsugu Aoyama, Hisashi Suda, Hiroto Narieda, Akira Sugawara, Akifumi Onodera,

Hereby sell, assign and transfer to DOWA METALTECH CO., LTD.,

a corporation of Japan,

having a place of business at 14-1, Sotokanda 4-chome, Chiyoda-ku, Tokyo 101-8617, Japan, its successors, assigns and legal representatives, the entire right, title and interest for the United States and all foreign countries, in and to any and all improvements which are disclosed in the application for United States Letters Patent, which has been executed by the undersigned concurrently herewith and is entitled

COPPER ALLOY SHEET AND METHOD FOR PRODUCING SAME (Attorney's Docket No. 10-210)

, and in and to said application and all divisional, continuing, substitute, renewal, reissue, and all other applications for Letters Patent which have been or shall be filed in the United States and all foreign countries on any of said improvements; and in and to all original and reissued patents which have been or shall be issued in the United States and all foreign countries on said improvements;

Agree that said Assignee may apply for and receive Letters Patent for said improvements in its own name; and that, when requested, without charge to but at the expense of said Assignee, its successors, assigns and legal representatives, to carry out in good faith the intent and purpose of this assignment, the undersigned will execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on any and all said improvements; execute all rightful oaths, assignments, powers of attorney and other papers; communicate to said Assignee, its successors, assigns, and representatives, all facts known to the undersigned relating to said improvements and the history thereof; and generally do everything possible which said Assignee, its successors, assigns or representatives shall consider desirable for aiding in securing and maintaining proper patent protection for said improvements and for vesting title to said improvements and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns and legal representatives; and

Covenant with said Assignee, its successors, assigns and legal representatives that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

Date	Jan. 12 2010	Werlin Gao	_(L.S.)
Date	Jan. 12, 2010	Tomotenga Aoyama	_(L.S.)
Date	Jan. 12, 2010	Hwashi Luda	(L.S.)
Date	Jan. 12 20/0	Hiroto herrieda	(L.S.)
Date	Jan. 12, 2010	ativa Lugawara	(L.S.)
Data	Jan 17 2016	Akifini Onodera PATE	N _t T _S)

RECORDED: 04/26/2010 REEL: 024287 FRAME: 0718